

MICRO-BUMPS TO ENHANCE LGA INTERCONNECTIONS

Abstract

An improved Land Grid Array interconnect structure is provided with the use of small metal bumps on the substrate electrical contact pad. The bumps interlock with segments of the fuzz button connection and increase the physical contact surface area between the contact pad and fuzz button. The improved contact reduces displacement of electrical contact points due to thermo-mechanical stress and lowers the required actuation force during assembly.